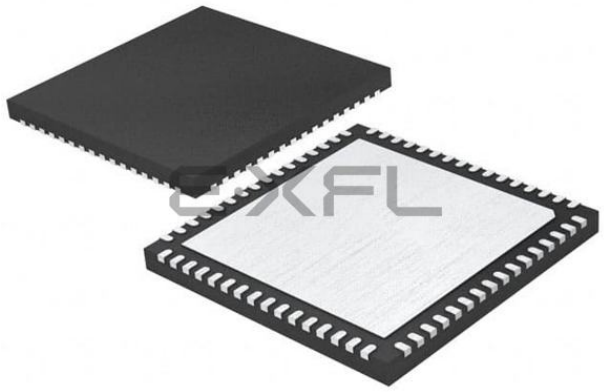

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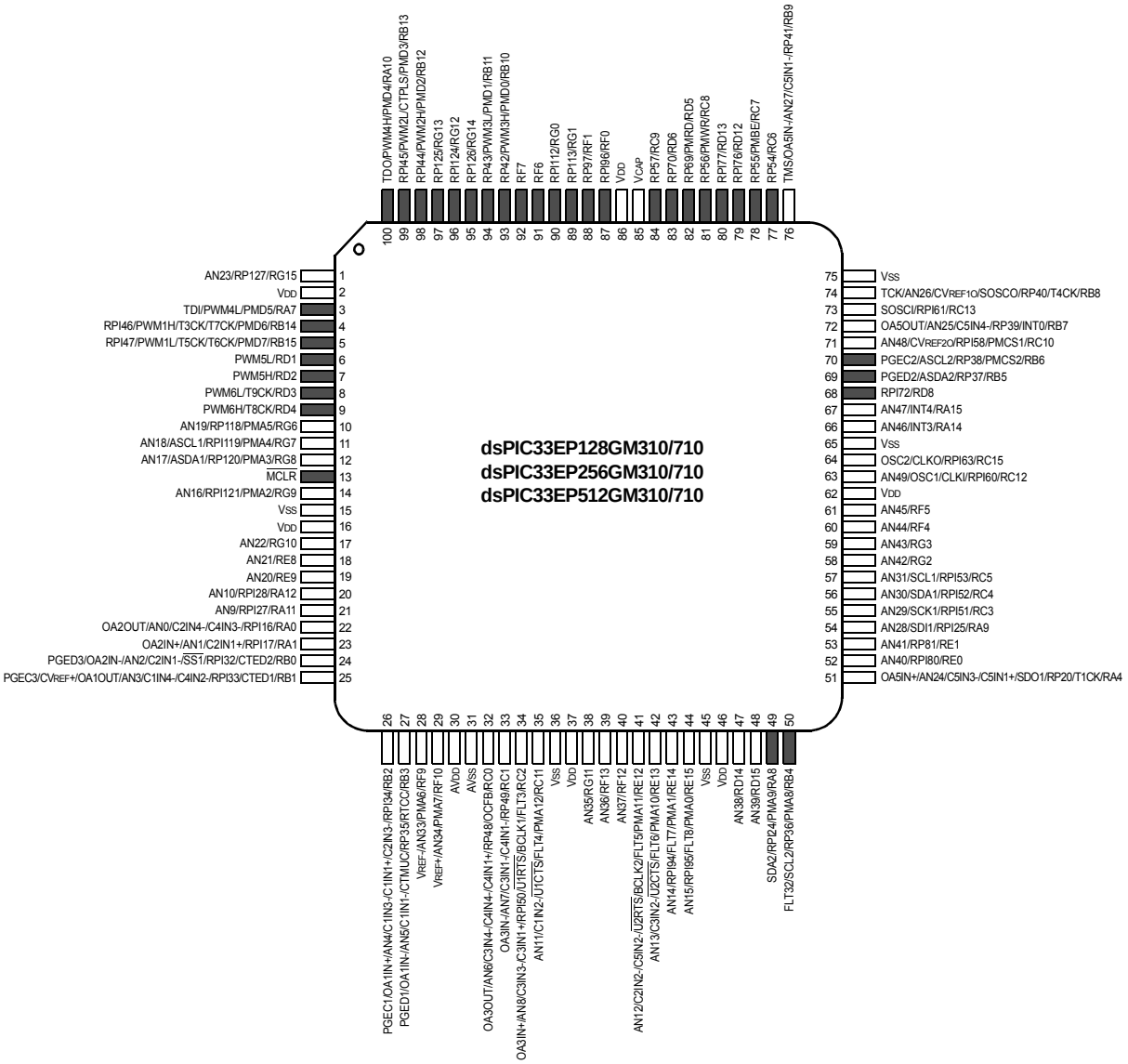
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gm706-i-pt

Pin Diagrams (Continued)

100-Pin TQFP(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Type	Buffer Type	PPS	Description
AN0-AN49	I	Analog	No	Analog Input Channels 0-49.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	I	ST/ CMOS	No	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	O	—	No	32.768 kHz low-power oscillator crystal output.
IC1-IC8	I	ST	Yes	Input Capture Inputs 1 through 8.
OCFA	I	ST	Yes	Output Compare Fault A input (for compare channels).
OCFB	I	ST	No	Output Compare Fault B input (for compare channels).
OC1-OC8	O	—	Yes	Output Compare 1 through 8.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
INT3	I	ST	No	External Interrupt 3.
INT4	I	ST	No	External Interrupt 4.
RA0-RA4, RA7-RA12, RA14-RA15	I/O	ST	Yes	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	Yes	PORTB is a bidirectional I/O port.
RC0-RC13, RC15	I/O	ST	Yes	PORTC is a bidirectional I/O port.
RD1-RD6, RD8, RD12-RD15	I/O	ST	Yes	PORTD is a bidirectional I/O port.
RE0-RE1, RE8-RE9, RE12-RE15	I/O	ST	Yes	PORTE is a bidirectional I/O port.
RF0-RF1, RF4-RF7, RF9-RF10, RF12-RF13	I/O	ST	No	PORTF is a bidirectional I/O port.
RG0-RG3, RG6-RG15	I/O	ST	Yes	PORTG is a bidirectional I/O port.
T1CK	I	ST	No	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	No	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
T6CK	I	ST	No	Timer6 external clock input.
T7CK	I	ST	No	Timer7 external clock input.
T8CK	I	ST	No	Timer8 external clock input.
T9CK	I	ST	No	Timer9 external clock input.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is not available on all devices. For more information, see the **"Pin Diagrams"** section for pin availability.

2: AVDD must be connected at all times.

TABLE 4-6: OUTPUT COMPARE REGISTER MAP (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC7CON1	093C	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC7CON2	093E	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC7RS	0940	Output Compare 7 Secondary Register																xxxx
OC7R	0942	Output Compare 7 Register																xxxx
OC7TMR	0944	Output Compare 7 Timer Value Register																xxxx
OC8CON1	0946	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC8CON2	0948	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC8RS	094A	Output Compare 8 Secondary Register																xxxx
OC8R	094C	Output Compare 8 Register																xxxx
OC8TMR	094E	Output Compare 8 Timer Value Register																xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-15: QEI1 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
QEI1CON	01C0	QEIEN	—	QEISIDL	PIMOD2	PIMOD1	PIMOD0	IMV1	IMV0	—	INTDIV2	INTDIV1	INTDIV0	CNTPOL	GATEN	CCM1	CCM0	0000
QEI1IOC	01C2	QCAPEN	FLTREN	QFDIV2	QFDIV1	QFDIV0	OUTFNC1	OUTFNC0	SWPAB	HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA	000x
QEI1STAT	01C4	—	—	PCHEQIRQ	PCHEQIEN	PCLEQIRQ	PCLEQIEN	POSOVIRQ	POSOVIEN	PCIIRQ	PCIIEN	VELOVIRQ	VELOVIEN	HOMIRQ	HOMIEN	IDXIRQ	IDXIEN	0000
POS1CNTL	01C6	POSCNT<15:0>																0000
POS1CNTH	01C8	POSCNT<31:16>																0000
POS1HLD	01CA	POSHLD<15:0>																0000
VEL1CNT	01CC	VELCNT<15:0>																0000
INT1TMRL	01CE	INTTMR<15:0>																0000
INT1TMRH	01D0	INTTMR<31:16>																0000
INT1HLDL	01D2	INTHLD<15:0>																0000
INT1HLDH	01D4	INTHLD<31:16>																0000
INDX1CNTL	01D6	INDXCNT<15:0>																0000
INDX1CNTH	01D8	INDXCNT<31:16>																0000
INDX1HLD	01DA	INDXHLD<15:0>																0000
QEI1GECL	01DC	QEIGEC<15:0>																0000
QEI1ICL	01DC	QEIIC<15:0>																0000
QEI1GECH	01DE	QEIGEC<31:16>																0000
QEI1ICH	01DE	QEIIC<31:16>																0000
QEI1LECL	01E0	QEILEC<15:0>																0000
QEI1LECH	01E2	QEILEC<31:16>																0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device was in Sleep mode
0 = Device was not in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **DMACERR:** DMA Controller Trap Flag bit
1 = DMA Controller trap has occurred
0 = DMA Controller trap has not occurred

bit 4 **MATHERR:** Math Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

REGISTER 11-9: RPINR12: PERIPHERAL PIN SELECT INPUT REGISTER 12

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **FLT2R<6:0>:** Assign PWM Fault 2 (FLT2) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

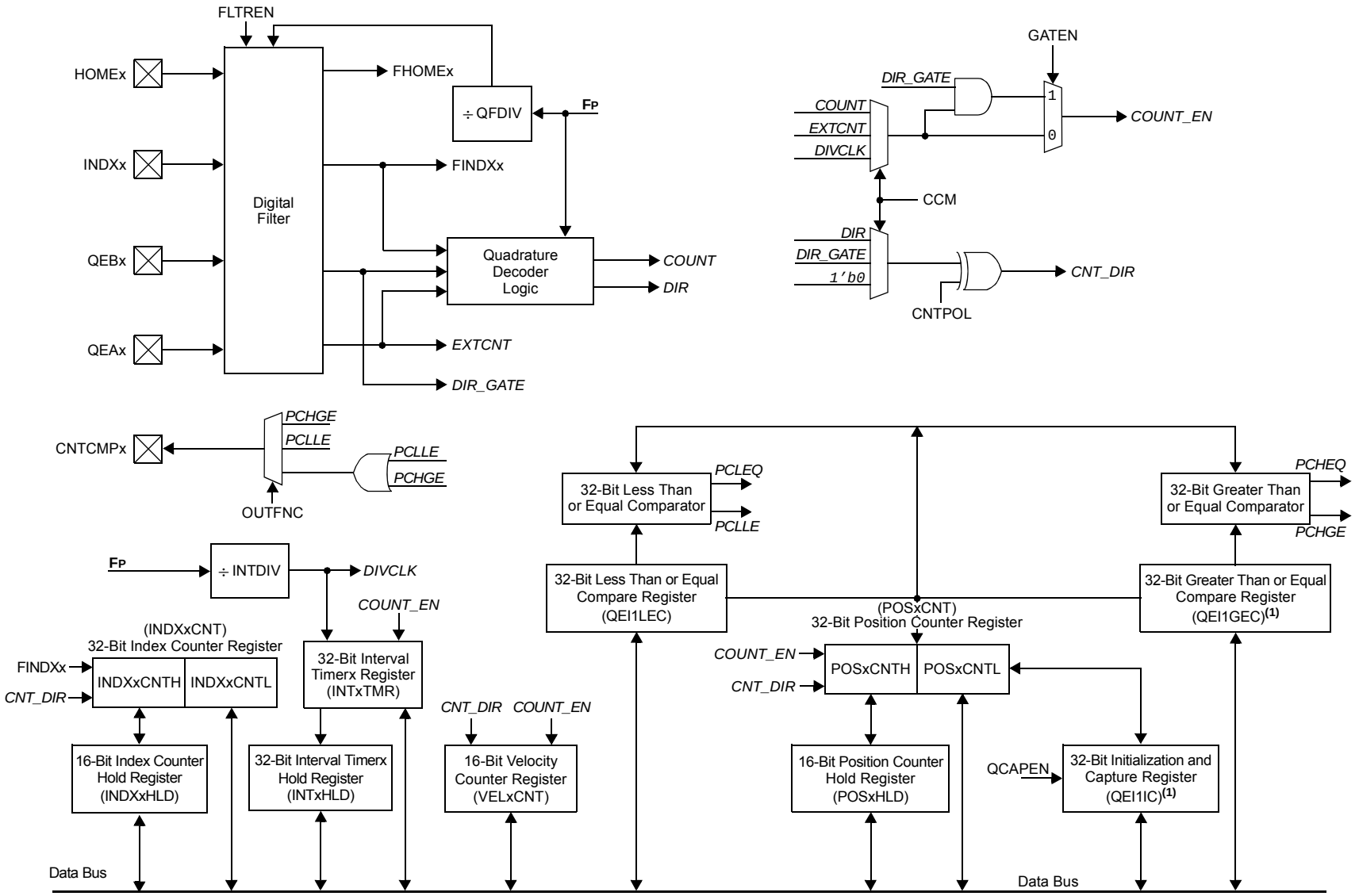
1111100 = Input tied to RPI124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **FLT1R<6:0>:** Assign PWM Fault 1 (FLT1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

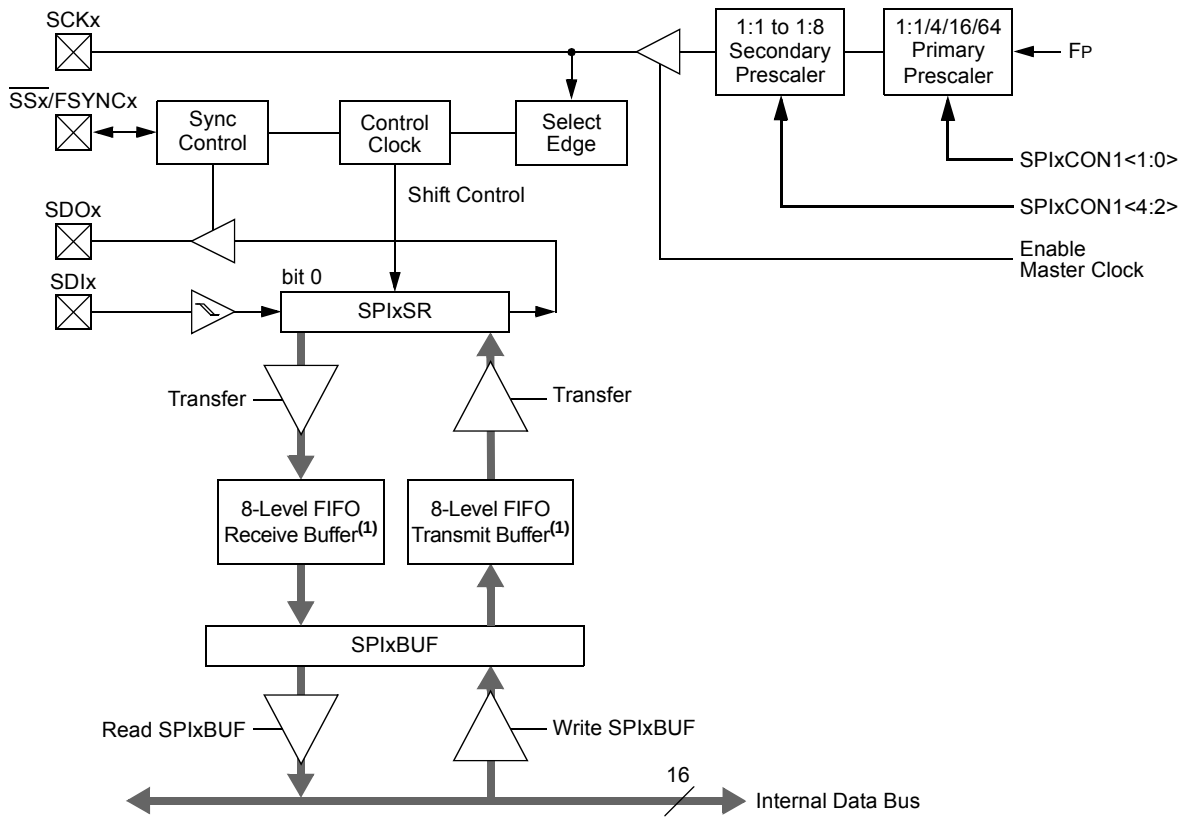
1111100 = Input tied to RPI124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

FIGURE 17-1: QEIx BLOCK DIAGRAM



Note 1: These registers map to the same memory location.

FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



Note 1: In Standard mode, the FIFO is only one level deep.

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **DISSCK:** Disable SCKx Pin bit (SPI Master modes only)
1 = Internal SPI clock is disabled, pin functions as I/O
0 = Internal SPI clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by the module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{SSx}$ pin is used for Slave mode
0 = $\overline{SSx}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

BUFFER 21-5: CANx MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 3<15:8>:** CANx Message Byte 3

bit 7-0 **Byte 2<7:0>:** CANx Message Byte 2

BUFFER 21-6: CANx MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 5<15:8>:** CANx Message Byte 5

bit 7-0 **Byte 4<7:0>:** CANx Message Byte 4

32.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

32.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

32.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

32.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 33-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage(3)**	3.0	—	3.6	V	
DC12	VDR	**RAM Data Retention Voltage(2)**	1.95	—	—	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0V-3.0V in 3 ms
DC18	VCORE	**VDD Core(3)** Internal Regulator Voltage	1.62	1.8	1.98	V	Voltage is dependent on load, temperature and VDD

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

2: This is the limit to which VDD may be lowered without losing RAM data.

3: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, op amp/comparator and comparator voltage reference will have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

TABLE 33-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

			Standard Operating Conditions (unless otherwise stated): Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
	CEFC	External Filter Capacitor Value(1)	4.7	10	—	μF	Capacitor must have a low series resistance (< 1 Ohm)

Note 1: Typical VCAP voltage = 1.8 volts when VDD ≥ VDDMIN.

TABLE 33-10: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		Any I/O Pin and $\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI18		I/O Pins with SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant	0.8 VDD	—	VDD	V	**(Note 3)**
		I/O Pins 5V Tolerant and $\overline{MCLR}$	0.8 VDD	—	5.5	V	**(Note 3)**
		I/O Pins with SDAx, SCLx	0.8 VDD	—	5.5	V	SMBus disabled
		I/O Pins with SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**Change Notification Pull-up Current**					
DI30			150	250	550	μA	VDD = 3.3V, VPIN = VSS
	ICNPD	**Change Notification Pull-Down Current(4)**					
DI31			20	50	100	μA	VDD = 3.3V, VPIN = VDD

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

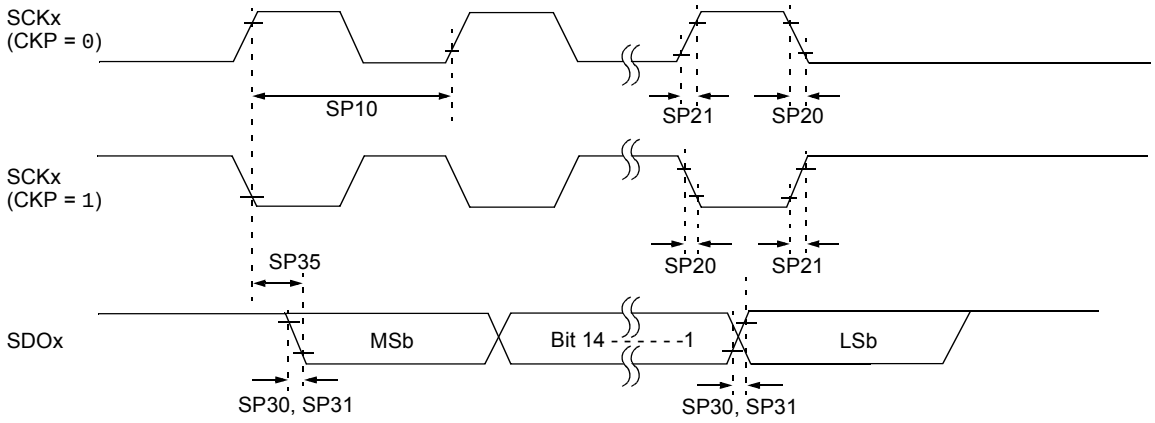
7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 33-32: SPI2 AND SPI3 MAXIMUM DATA/CLOCK RATE SUMMARY

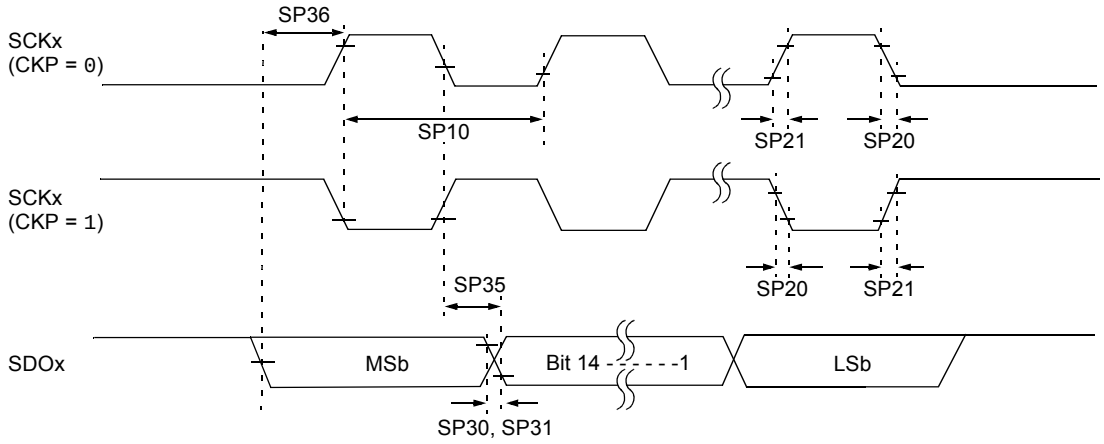
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 33-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 33-34	—	1	0,1	1
9 MHz	—	Table 33-35	—	0	0,1	1
15 MHz	—	—	Table 33-36	1	0	0
11 MHz	—	—	Table 33-37	1	1	0
15 MHz	—	—	Table 33-38	0	1	0
11 MHz	—	—	Table 33-39	0	0	0

FIGURE 33-15: SPI2 AND SPI3 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

FIGURE 33-16: SPI2 AND SPI3 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

TABLE 33-33: SPI2 AND SPI3 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCKx Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 33-33: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

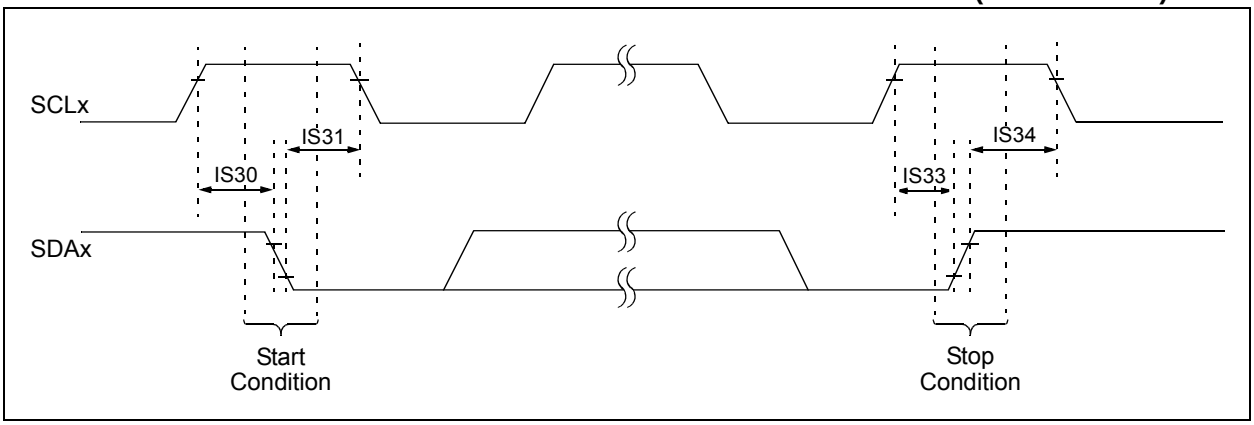


FIGURE 33-34: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)

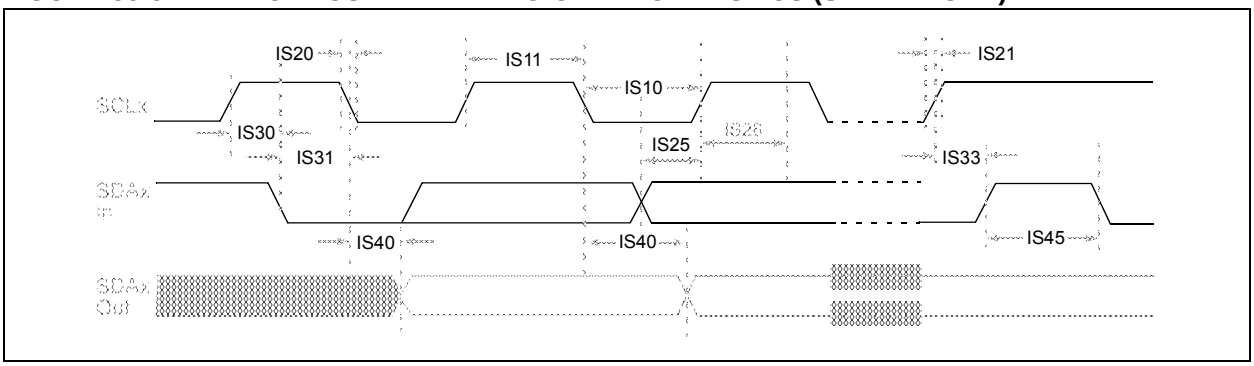


TABLE 33-49: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param. No.	**Symbol**	**Characteristic(3)**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(1)	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25		µs	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	
IS51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 2)**

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

2: The Typical value for this parameter is 130 ns.

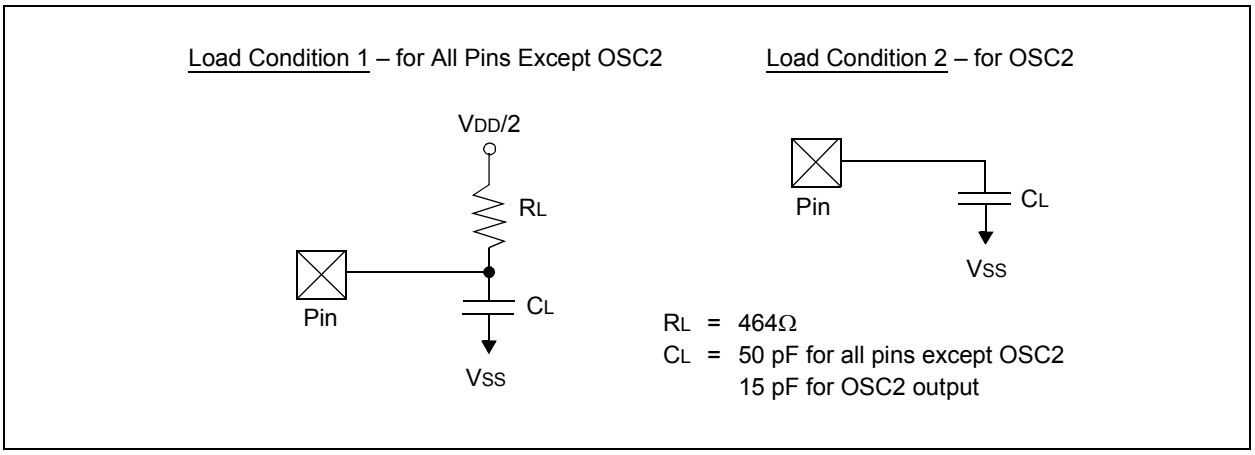
3: These parameters are characterized, but not tested in manufacturing.

TABLE 33-55: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CTMU Current Source							
CTMUI1	IOUT1	Base Range	280	550	830	nA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range	2.8	5.5	8.3	µA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range	28	55	83	µA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range	280	550	830	µA	CTMUICON<9:8> = 00
CTMUFV1	VF		—	0.77	—	V	
CTMUFV2	VFVR		—	-1.38	—	mV/°C	

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

FIGURE 33-37: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



NOTES: